

CLAIMS

1. An interposer to be located between a package substrate made of resin and an IC chip, having a plurality of through holes and in which a through hole conductor for connecting said
5 package substrate with the IC chip electrically is formed, wherein Young's modulus of insulation base material constituting said interposer is 55 to 440GPa and the thickness of said insulation base material is the thickness of the package substrate \times 0.05 or more to the thickness of the package
10 substrate \times 1.5 or less.
2. The interposer according to claim 1 wherein the thickness of said insulation base material is the thickness of core of the package substrate \times 0.08 or more.
3. The interposer according to claim 1 or 2 wherein the size
15 of said insulation base material is equal to or larger than the projection area of an electronic component loaded on the interposer and equal to or less than the projection area of the package substrate.
4. The interposer according to claim 1, 2, 3 wherein of external
20 electrode terminals formed in the IC chip, arrangement of the through holes in said insulation base material connected to a power source terminal and a ground terminal is in the form of a grid or in a staggered fashion.
5. The interposer according to claim 1-4 wherein said package
25 substrate is a multilayer printed wiring board.
6. The interposer according to claim 1-5 wherein said through hole conductor is made of metal plating.
7. The interposer according to claim 1-5 wherein said through hole conductor is made of metallic paste.
- 30 8. The interposer according to claim 1-7 wherein as regards the sectional shape of a through hole in the insulation base material, the diameter of an opening in at least an end face is equal to or larger than the diameter of a hole in the center

of the through hole.

9. A multilayer printed wiring board having any one of the interposers according to claim 1-8.